Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**1**

**3**

**2**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .015” X .015”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .078” X .078” DATE: 3/21/22**

**MFG: MOTOROLA / ON SEMI THICKNESS .015” P/N: MCC7915**

**DG 10.1.2**

#### Rev B, 7/19/02